Golden List of Reviewers for 2023

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Jong-Uk	Bae	LG Display	South Korea
Chang-Ki	Baek	POSTECH	South Korea
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Huipeng	Chen	Fuzhou University	China
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Hsiao-Hsuan	Hsu	National Taipei University of Technology	Taiwan
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Vita	Hu	National Taiwan University	Taiwan
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Yuanyuan	Hu	Hunan University	China
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Mengyuan	Hua	Southern University of Science and Technology	China
Qilin	Hua	Beijing Institute of Technology	China
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Chun-Yuan	Huang	National Taitung University	Taiwan
Fei	Huang	South China University of Technology	China
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Peng	Huang	Peking University	China
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Chen	Zhang	IBM	United States
Mingyang	Zhang	University of New Mexico College of Arts and Sciences	United States
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Liang	Zhao	Zhejiang University	China
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Qiang	Zhao	Nanjing University	China
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Yuda	Zhao	Zhejiang University	China
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Hai	Zhou	Dongguan University of Technology	China
Hang	Zhou	Peking University	China

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Ye	Zhou	Shenzhen University	China
Yichun	Zhou	Xidian University	China
Zheng	Zhou	Peking University	China
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Huipeng	Chen	Fuzhou University	China
Jen-Sue	Chen	National Cheng Kung University	Taiwan
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Lin	Chen	Fudan University	China
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Ran	Cheng	Zhejiang University	China
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Sungju	Choi	Kookmin University	South Korea
Woo Young	Choi	Seoul National University	South Korea
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Nadim	Chowdhury	Massachusetts Institute of Technology	United States
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Uttiya	Chowdhury	Boeing Research & Technology	United States
Rongming	Chu	Pennsylvania State University	United States
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Chengyuan	Dong	Shanghai Jiao Tong University	China
Shurong	Dong	Zhejiang University	China
Yuan	Dong	Shanghai University	China
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Meng	Duan	Synopsys Inc.	United Kingdom
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Xiaosheng	Fang	Fudan University	China
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Genquan	Han	Xidian University	China
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Kijeong	Han	Cree | Wolfspeed	United States
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Yuanyuan	Hu	Hunan University	China
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Huaiyu	Ye	Southern University of Science and Technology	China
Jiandong	Ye	Nanjing University	China
Mustafa	Yelten	Istanbul Teknik Universitesi	Turkey
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Junsin	Yi	Sungkyunkwan University - Suwon Campus	South Korea
Hanbin	Ying	Georgia Institute of Technology	United States
Hin-Lap	Yip	City University of Hong Kong	China
Hocheon	Yoo	Gachon University	South Korea
Jongwoon	Yoon	Sogang University	South Korea
Junghoo	Yoon	Korea Institute of Science and Technology	South Korea
Jun-Sik	Yoon	POSTECH	South Korea
Sungmin	Yoon	Kyung Hee University	South Korea
Tae-Sik	Yoon	Ulsan National Institute of Science and Technology	South Korea
Sheng-Joue	Young	National United University	United States
Hao	Yu	IMEC	Belgium
Shimeng	Yu	Georgia Institute of Technology	United States
Xiao	Yu	Zhejiang University	China
Xinxin	Yu	Nanjing Electronic Devices Institute	China
Zhouchangwan	Yu	Stanford University	United States
Mengyang	Yuan	Massachusetts Institute of Technology	United States
XueSong	Yuan	University of Electronic Science And Technology of China	China
Ruifeng	Yue	Tsinghua University	China
Sabahattin	Yurt	QUALCOMM Inc.	United States
Salahuddin	Zafar	Bilkent University Department of Electrical and Electronics Engineering	Turkey
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Zhigang	Zang	Chongqing University	China
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Dongzhi	Zhang	China University of Petroleum (East China)	China
Feng	Zhang	Xiamen University	China
Fujun	Zhang	Institute of Optoelectronic Technology	China
Han	Zhang	Shenzhen University	China
Heqiu	Zhang	Dalian University of Technology	China
Jie	Zhang	Xiamen University	China
Jishen	Zhang	National University of Singapore	Singapore
Kai	Zhang	Nanjing Electronic Devices Institute	China
Lining	Zhang	Peking University	China
Lining	Zhang	Shenzhen University	China
Long	Zhang	Southeast University	China
Meng	Zhang	Shenzhen University	China
Min	Zhang	Peking University	China
Qi	Zhang	Huazhong University of Science and Technology	China
Shengli	Zhang	Nanjing University of Science and Technology	China
Wei	Zhang	Liverpool John Moores University	United Kingdom
Wentong	Zhang	University of Electronic Science and Technology of China	China
Yating	Zhang	Tianjin University	China
Yue	Zhang	Spintronics Interdisciplinary Center, Beihang University	China
Yuhao	Zhang	Virginia Polytechnic Institute and State University	United States
Yuqing	Zhang	The Hong Kong University of Science and Technology	Hong Kong
Zexuan	Zhang	Cornell University	United States
Zi-Hui	Zhang	Hebei University of Technology	China
Chen	Zhang	IBM	United States
Mingyang	Zhang	University of New Mexico College of Arts and Sciences	United States
Chun	Zhao	Xi’an Jiaotong-Liverpool University	China
Ding	Zhao	Chinese Academy of Sciences	China
Liang	Zhao	Zhejiang University	China
Lixia	Zhao	Institute of Semiconductors Chinese Academy of Sciences	China
Qiang	Zhao	Nanjing University	China
Xiaojin	Zhao	Shenzhen University	China
Yi	Zhao	Zhejiang University	China
Yuda	Zhao	Zhejiang University	China
Dongqi	Zheng	Apple Inc.	United States
Jun	Zheng	Institute of Semiconductors Chinese Academy of Sciences	China
Xin	Zheng	Stanford University	United States
Xun	Zheng	University of California Santa Barbara	United States
Zheyang	Zheng	Hong Kong University of Science and Technology	Hong Kong
Zijian	Zheng	The Hong Kong Polytechnic University	Hong Kong
Zijie	Zheng	National University of Singapore - Kent Ridge Campus	Singapore
Haizheng	Zhong	Beijing Institute of Technology	China
Kuncai	Zhong	Hunan University	China
Changjian	Zhou	South China University of Technology	China
Dayu	Zhou	Dalian University of Technology	China
Hai	Zhou	Dongguan University of Technology	China
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Jiuren	Zhou	Xidian University	China
Peng	Zhou	Fudan University	China
Qi	Zhou	University of Electronic Science and Technology of China	China
Shengjun	Zhou	Wuhan University	China
Ye	Zhou	Shenzhen University	China
Yichun	Zhou	Xidian University	China
Zheng	Zhou	Peking University	China
Zuopu	Zhou	National University of Singapore - Kent Ridge Campus	Singapore
Jiejie	Zhu	Xidian University	China
Xi	Zhu	University of Technology Sydney	Australia
Zhongtao	Zhu	University of Notre Dame	United States
Fei	Zhuge	Ningbo Institute of Materials Technology and Engineering Chinese Academy of Sciences	China
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Thomas	Zimmer	Université de Bordeaux	France
Cezar	Zota	IBM Zurich Research Laboratory	Switzerland
Jie	Zou	Fudan University	China
Yousheng	Zou	Nanjing University of Science and Technology	China
Ahmad	Zubair	Intel Corporation	United States
Nerija	Zurauskiene	State Research Institute Center for Physical Sciences and Technology	Lithuania